**Ultra-Low Capacitance ESD Protection Device** 

#### **Features**

□ Transient protection for high-speed data lines IEC 61000-4-2 (ESD) ±25kV (Air)

±17kV (Contact)

IEC 61000-4-4 (EFT) 40A (5/50 ns) Cable Discharge Event (CDE)

- □ Package optimized for high-speed lines
- □ Ultra-small package (2.5mmx1.0mmx0.55mm)
- □ Protects four data lines
- □ Low capacitance: 0.40pF Typical(I/O-GND)
- □ Low leakage current: 0.1uA@V<sub>RWM</sub> (Typical)
- □ Low clamping voltage
- □ Each I/O pin can with stand over 1000 ESD strikes for ±8kV contact discharge

#### Description

T0514SP is an ultra-low capacitance Transient Voltage Suppressor (TVS) designed to provide electrostatic discharge (ESD) protection for high-speed data interfaces. With typical capacitance of 0.4 pF only, T0514SP is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4 (±15kV air, ±8kV contact discharge), IEC 61000-4-4 (electrical fast transient - EFT) (40A,5/50 ns), very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

T0514SP uses ultra-small DFN2510-10L package. Each T0514SP device can protect four high-speed data lines The combined features of ultra-low capacitance, ultra-small size and high ESD robustness make T0514SP ideal for high-speed data ports and high-frequency lines (e.g.,HDMI & DVI) applications. The low camping voltage of the T0514SP guarantees a minimum stress on the protected IC.

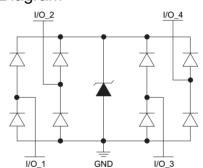
#### **Applications**

- □ Serial ATA
- PCI Express
- □ Desktops, Servers and Notebooks
- MDDI Ports
- □ USB 2.0/3.0/3.1 Power and Data Line Protection
- Display Ports
- ☐ High Definition Multi-Media Interface (HDMI1.4/2.0)
- □ Digital Visual Interfaces (DVI)

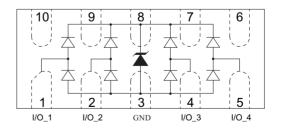
#### **Mechanical Characteristics**

- □ DFN2510-10L package
- □ Flammability Rating: UL 94V-0
- □ Marking: Part number, Date
- □ Packaging: Tape and Reel

## Circuit Diagram



#### Pin Configuration



DFN2510-10L (Top View)

Document ID : DS-22V16 Revised Date : 2017/07/20

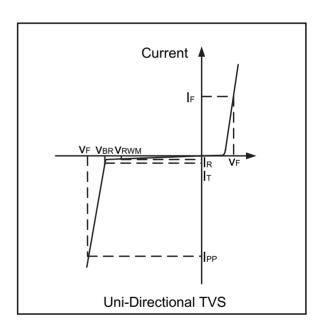


# **Absolute Maximum Rating**

Symbol	Parameter	Value	Units
I <sub>PP</sub>	Peak Pulse Current(tp=8/20us)(I/O pins)	А	
V <sub>ESD</sub>	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	±25 ±17	kV
T <sub>OPT</sub>	Operating Temperature	-55/+125	°C
T <sub>STG</sub>	Storage Temperature	-55/+150	°C

# Electrical Characteristics (T = 25 °C)

Symbol	Parameter
$V_{RWM}$	Nominal Reverse Working Voltage
$I_R$	Reverse Leakage Current @V <sub>RWM</sub>
$V_{BR}$	Reverse Breakdown Voltage @I T
Ι <sub>Τ</sub>	Test Current for Reverse Breakdown
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
I <sub>PP</sub>	Maximum Peak Pulse Current
C <sub>ESD</sub>	Parasitic Capacitance
$V_R$	Reverse Voltage
f	Small Signal Frequency
I <sub>F</sub>	Forward Current
$V_{F}$	Forward Voltage @l <sub>F</sub>



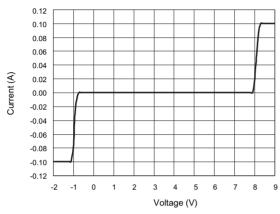
Symbol	Test Condition	Minimum	Typical	Maximum	Units
$V_{RWM}$				5.0	V
I <sub>R</sub>	V <sub>RWM</sub> = 5V,T = 25 C Between I/O and GND		0.1	1.0	μΑ
$V_{BR}$	$I_T$ = 1mA Between I/O and GND	6.0	8.0	10.0	V
V <sub>C</sub>	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs Between I/O and GND			12	V
C <sub>ESD</sub>	V <sub>R</sub> = 0V, f = 1MHz Between I/O and GND		0.4	0.5	pF
C <sub>ESD</sub>	V <sub>R</sub> = 0V, f = 1MHz Between I/O and I/O		0.05	0.08	pF

Document ID : DS-22V16 Revised Date : 2017/07/20

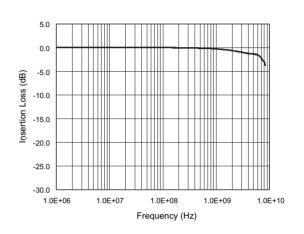


#### **Ultra-Low Capacitance ESD Protection Device**



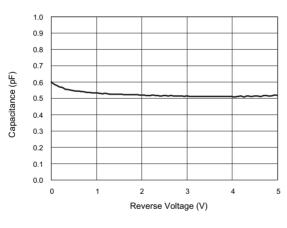


## Insertion Loss S21 of I/O to GND

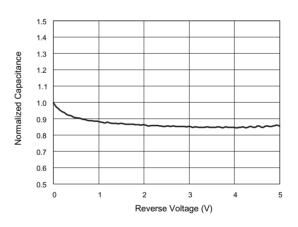


## Capacitance vs. Voltage of I/O to GND (f = 1MHz)

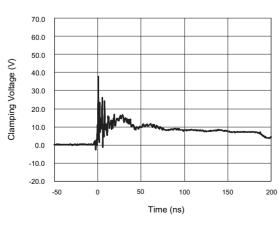
Capacitance vs. Reverse Voltage



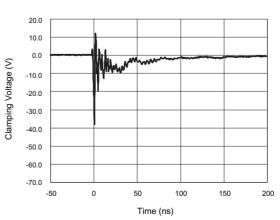
Normalized Capacitance vs. Reverse Voltage



# ESD Clamping of I/O to GND (+8kV Contact per IEC 61000-4-2)



ESD Clamping of I/O to GND (-8kV Contact per IEC 61000-4-2)



Document ID : DS-22V16 Revised Date : 2017/07/20

**Ultra-Low Capacitance ESD Protection Device** 

### **Application Information**

#### Pin Connection in PCB

T0514SP provides ESD protection for four data lines simultaneously. The pin connection is shown in the figure below.

Four parallel data lines, from inner IC to I/O port connector, coule connect to T0514SP four I/O pins directly. Pin 3&8 of T0514SP is the GND pin, which should connect to the GND of PCB. The wire should be as short as possible in order to minimize the parasitic inductance.

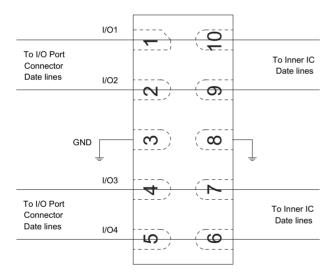


Figure 1 T0514SP pin connection in PCB

#### **PCB Layout Guidelines**

For optimum ESD protection and the whole circuit performance, the following PCB layout guidelines are recommended:

- □ T0514SP GND pin to the PCB GND rail path should be as short as possible. It could reduce the ESD transient return path to GND.
- □ The vias connecting T0514SP GND pins to the PCB GND should be wide
- Place T0514SP as close to the connector port as possible. It could reduce the parasitic inductance and restrict ESD coupling into adjacent traces.
- Avoid running critical signals near board edges.

Document ID: DS-22V16 Revised Date: 2017/07/20

**Ultra-Low Capacitance ESD Protection Device** 

## **Application Information** TMDS\_D2+ TMDS\_D2+ TMDS\_D2-TMDS\_D2-T0514SP $(\underline{\infty}$ TMDS\_D1+ TMDS\_D1+ TMDS\_D1-<del>(</del><u>o</u> TMDS\_D1-TMDS\_D0+ TMDS\_D0+ HDMI CONNECTOR TMDS\_D0-TMDS\_D0-T0514SP $(\underline{\infty}$ TMDS\_CLK+ TMDS\_CLK+ TMDS\_CLK TMDS\_CLK-CEC CEC NC T0514TL SCL 9 SCL SDA 5 SDA **GND** +5V <sup>\_\_\_</sup> 4 က HTP\_D HTP\_D

Figure 2 Layout Top View for HDMI Interface With T0514SP & T0514TL

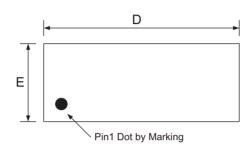
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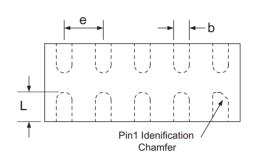


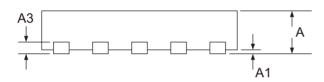
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# Package Outline

DFN2510-10L package Thermally-Enhanced MSL-1 Level







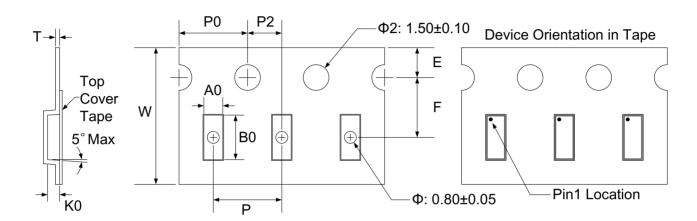
Package Dimensions (Controlling dimensions are in millimetes)

Symbol	Dimensio	ons (mm)	Dimensions (inch)		
Symbol	Minimum Maximum		Minimum	Maximum	
А	0.500	0.600	0.020	0.024	
A1	0.000	0.050	0.000	0.002	
A3	0.150	REF.	0.006REF.		
b	0.150	0.250	0.006	0.010	
D	2.450	2.550	0.096	0.100	
Е	0.950	1.050	0.037	0.041	
е	0.500 BSC		0.020 BSC		
L	0.300	0.400	0.012 0.016		

Document ID : DS-22V16 Revised Date : 2017/07/20

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# Tape and Reel Specification



Symbol	W	A0	В0	K0	E	F	Р	P0	P2	Т
Dimensions (mm)	8.00+0.3 -0.1	1.23±0.05	2.7±0.05	0.7±0.05	1.75±0.1	3.5±0.05	4.0±0.1	4.0±0.1	2.0±0.05	0.25±0.02

# Marking Codes



Or



#### Note:

(1) "14S" is part number, while "YWW" is date code.

# Note:

- (1) "14S" is part number, fixed.
- (2) "XXX" is the last 3 characters of the wafer's Lot No.,

# **Ordering Information**

Part Number	Working Voltage	Quantity Per Reel	Reel Size	
T0514SP	5V	3,000	7 Inch	

"Y" is the internal code.

Document ID : DS-22V16 Revised Date : 2017/07/20



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